Product Change Notification / BLAS-30JBNQ938

Date:

22-Mar-2024

Product Category:

16-Bit - Microcontrollers And Digital Signal Controllers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6430 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected dsPIC33CK64MP102xxx, dsPIC33CK64MC102xxx, dsPIC33CK32MC102xxx, dsPIC33CK256MC502xxx, dsPIC33CK128MC502xxx, dsPIC33CK256MC102xxx, dsPIC33CK128MC102xxx and dsPIC33CK32MP102xxx device families available in 28L UQFN (4x4x0.6mm) package.

Affected CPNs:

BLAS-30JBNQ938_Affected_CPN_03222024.pdf
BLAS-30JBNQ938_Affected_CPN_03222024.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected dsPIC33CK64MP102xxx, dsPIC33CK64MC102xxx, dsPIC33CK32MC102xxx, dsPIC33CK256MC502xxx, dsPIC33CK128MC502xxx, dsPIC33CK256MC102xxx, dsPIC33CK128MC102xxx and dsPIC33CK32MP102xxx device families available in 28L UQFN (4x4x0.6mm) package.

Pre and Post Change Summary:

	Pre Change	**Post Change**
Assembly Site	Microchip Technology Thailand (Branch) / (MMT)	Microchip Technology Thailand (Branch) / (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	HR-5104T-25	HR-5104T-25
Molding Compound Material	G700LTD	G700LTD
Lead-Frame Material	EFTEC64T	EFTEC64T
Lead-Frame Paddle Size	110x110mm	110x110mm

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status: In Progress

Estimated First Ship Date: May 20, 2024 (date code: 2421)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2023					**>**	**March 2024**					**>**	**May 2024**				
Workweek	27	28	29	30	31		09	10	11	12	13		18	19	20	21	22
Initial PCN Issue Date					x												
Qual Report Availability										x							
Final PCN Issue Date										x							
Estimated Implementation Date																x	

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: July 31, 2023: Issued initial notification.
March 22, 2024: Issued final notification. Attached the Qualification Report. Updated affected parts list. Provided estimated first ship date to be on May 20, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_BLAS-30JBNQ938_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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